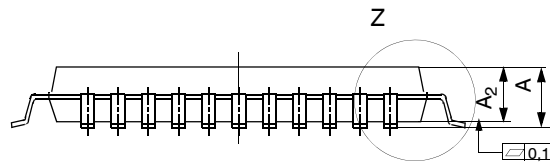



**Package PQ4-LQFP44
(10 x 10)**
**MDS
750**

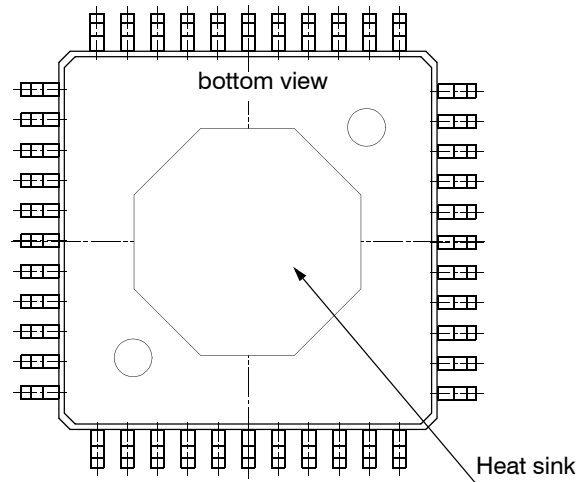
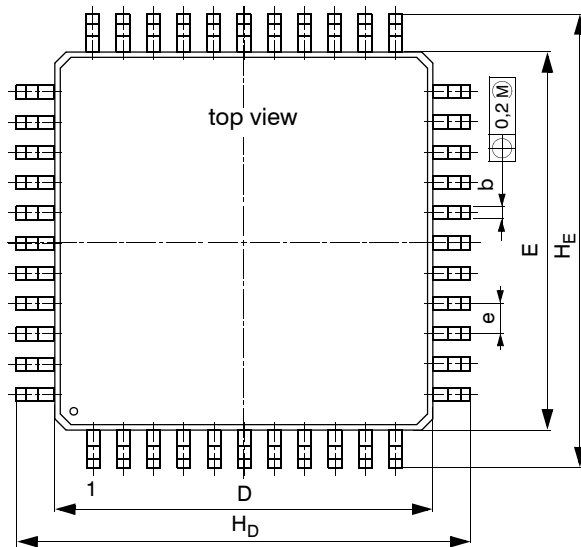
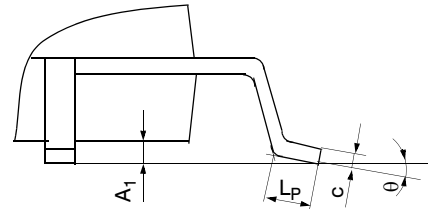
 Supersedes
Edition 11.97

Dimensions in millimetres

Based on JEDEC: MS-026

1 Dimensions


Detail Z



Dimensions of Sub-Group B1	
e_{nom}	0,80
A_{max}	1,60
b_{Pmin}	0,30
b_{Pmax}	0,45
H_{Emin}	11,85
H_{Emax}	12,15
H_{Dmin}	11,85
H_{Dmax}	12,15
L_{Pmin}	0,45

2 Weight $\leq 0,5$ g

3 Package Body Material Low Stress Epoxy

4 Lead Material FeNi-Alloy or Cu-Alloy

5 Lead Finish solder plating

6 Lead Form Z-bends

Dimensions of Sub-Group C1	
A_{min}	–
A_{1min}	0,05
A_{1max}	0,15
A_{2min}	1,35
A_{2max}	1,45
c_{min}	0,09
c_{max}	0,20
D_{min}	9,75
D_{max}	10,25
E_{min}	9,75
E_{max}	10,25
θ_{min}	0°
θ_{max}	7°

Zentrum Mikroelektronik Dresden AG

Editor: signed Schoder

Date: 30.04.2002

Check: signed Marx

Quality: signed Gersdorf

 Doc-No.
QS-000750-HD-02